

Best for Core i7



Module | Xtream Series

Team Triple Channel Xtream DDR3 2000

The Team Xtream Triple channel 2000 series comes in 2 different flavors, one with the high bandwidth and another one is with super low latencies to enhance your overclocking experience. Results from this product is breath taking and tools to make your way entering different level of overclocking experience.

Team Group utilizes the most sophisticated IC sorting and heat dissipation technology to gain more overclocking margin from our products. The latest heat dissipation technology, force the heat from the chips to go through a specially designed heat tape. And then the excess heat is transferred into a thermal vaporizer heat spreader. This process can provide an even cooling environment for the modules performing at super high speed



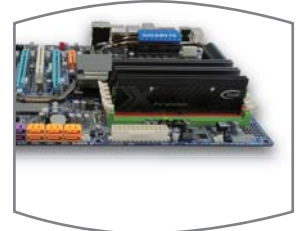
Main Feature

- Fully compatible with Intel X58-based DDR3 motherboards
- High frequency and Super Low latency
- XMP Ready for Core™ i7 Processors
- Lifetime Warranty [10 years for German, Austria and France]
- RoHS Compliant
- Large capacity: 6GB Kit (3x2GB), 2GB Kit (3x1GB)
- 100% Tested and Verified
- Equipped super thermal conduction heat spreader

Specification

Triple Channel Xtream DDR3 2000

Item	Specification
P/N	TXD36144M2000HC9TC、TXD33072M2000HC9TC
Suitable for	Desktop PCs
Module Type	240Pin Unbuffered DIMM Non ECC
DRAM Density	128x8
Capacity	6GB Kit (3x2GB)、3GB Kit (3x1GB)
Data transfer bandwidth	16,000MB/Sec (PC3 16000)
CL-value	9-9-9-24-2T
Working voltage	1.65V
XMP/EPP	Intel XMP Profile 9-9-9-24 at 2000MHz
PCB	8-layer PCB
Extra features	Super Thermal Conduction Aluminum heat-sink
Warranty	Lifetime warranty



Triple Channel Xtream DDR3 2000

Item	Specification
P/N	TXD36144M2000HC7TC、TXD33072M2000HC7TC
Suitable for	Desktop PCs
Module Type	240Pin Unbuffered DIMM Non ECC
DRAM Density	128x8
Capacity	6GB Kit (3x2GB)、3GB Kit (3x1GB)
Data transfer bandwidth	16,000MB/Sec (PC3 16000)
CL-value	7-8-7-20-2T
Working voltage	1.65V
XMP/EPP	Intel XMP Profile 7-8-7-20 at 2000MHz
PCB	8-layer PCB
Extra features	Super Thermal Conduction Aluminum heat-sink

Ordering Information

Team P/N	Capacity	Description
TXD36144M2000HC9TC	6GB Kit(3*2GB)	PC3 16000 DDR3 2000MHz 9-9-9-24
TXD33072M2000HC9TC	3GB Kit(3*1GB)	PC3 16000 DDR3 2000MHz 9-9-9-24
TXD36144M2000HC7TC	6GB Kit(3*2GB)	PC3 16000 DDR3 2000MHz 7-8-7-20
TXD33072M2000HC7TC	3GB Kit(3*1GB)	PC3 16000 DDR3 2000MHz 7-8-7-20



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